

FLUX SK10

The solder-active intermediate protector for printed circuit boards.

1. GENERAL DESCRIPTION

Lacquer-like flux solution on a base of natural resins with no additives.

2. FEATURES

KONTAKT CHEMIE Flux SK 10 forms an evenly spreading, transparent protective film. Soft-solderable metals (e.g. copper, tin, lead, brass, steel) are protected against corrosion. Solderability is maintained, the protective film does not need to be removed prior to soldering, since it also acts as a highly effective flux.

3. APPLICATIONS

KONTAKT CHEMIE Flux SK 10 is used e.g. in the interim storage of bare PCBs and for parts intended for soldering up, such as solder terminals or cable shoes. It is used to maintain the solderability of lead cast parts (accumulator manufacture) and semi-finished products made from non-ferrous heavy metals.

4. DIRECTIONS

KONTAKT CHEMIE Flux SK 10 is best used from an aerosol for small series and service applications. Unusually for lacquers, the spray is filled with the environmentally friendly propellant carbon dioxide. With this product, it is not necessary to clean the valve by spraying the can upside-down!

For series applications KONTAKT CHEMIE Flux SK 10 can be applied in the delivered form with a paint brush, by dip-coating or spraying. In the case of immersion-coating the immersion time and withdrawal speed should be fixed. The faster the withdrawal speed, the thicker the film.

KONTAKT CHEMIE Flux SK 10 is used for temporary corrosion protection and to maintain the solderability of soft-solderable metals. The resin used, protects against corrosion in dry environments and prevents the metals from coming into direct contact with dust, dirt and fingerprints.

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The lack is also frequently used as a protective coating for PCBs which are mainly used in dry environments. In very damp environments, however, the resin undergoes slow hydrolysis, as a result the good corrosion protection properties and electrical properties are lost. For such applications we recommend using the proven PCB protective coating KONTAKT CHEMIE Plastik 70, KONTAKT CHEMIE Urethane 71 or KONTAKT CHEMIE Silisol 73.

If other coatings are to be applied after the soldering process, the film of solderable lacquer must be removed. Cleaners based on alcohols, glycol ethers or hydrocarbones such as KONTAKT CHEMIE Label Off 50 are best for this. For smaller piece numbers the spray cleaner KONTAKT CHEMIE Kontakt PCC is highly recommended.

When using KONTAKT CHEMIE Flux SK 10 the workplace must be well-ventilated. Installations must be suitable for the use of lacquers with flammable solvents. Additional safety information can be found in the safety data sheet.

5. TYPICAL PRODUCT DATA

Aerosol

Flash point	:	< 0 °C
Density at 20 °C FEA 605	:	0.82 g/cm ³
Coverage at 15µm film thickness	:	0.7 m ² / 200 ml can

Bulk

Flash point	:	< 0 °C
Density at 20 °C ASTM D 891	:	0.81 g/cm ³
Coverage at 15 µm film thickness	:	4.7 m ² / l

Dry film properties

Flux type DIN 8511 T2	:	F-SW31
Colour	:	Transparent, colourless-yellowish
Drying time In House method	:	30 min
Usable temperature range	:	0 °C to 60 °C

6. APPROVALS:

NATO stock number	:	3439-12-160-1674
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7. PACKAGING

Aerosol : 200 ml
400 ml

All statements in this publication are based on service experience and/or laboratory testing. Because of the wide variety of equipment and conditions and the unpredictable human factors involved, we recommend that our products be tested on-the-job prior to use. All information is given in good faith but without warranty neither expressed nor implied.

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We recommend you to register on this website for this product so you will be able to receive any future updated version automatically.

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